

Title (en)

CENTERING DEVICE FOR THE REALIZATION OF THE PIN INSERTION OF A MULTIPIN CASE

Publication

EP 0228119 B1 19910403 (FR)

Application

EP 86202170 A 19861204

Priority

FR 8518471 A 19851213

Abstract (en)

[origin: US4741090A] Centering device for inserting pins in a multipin housing designed to receive an integrated circuit, whose pins are in the form of stems fitted with flat heads. The stem goes through a plane part, called the housing substrate, through holes which have first been metallized, with the pins protruding from one of the faces of the substrate by a length sufficient to ensure the fastening of the housing. The flat head bears upon the other face of the substrate via a metal preform of an alloy which is suitable for ensuring the fusion or melting for fastening the pins. This centering device consists of three parts. The first part is formed by a first metallic plate; the second part is formed by a second metallic plate used for calibrating the centering of the pins, said metallic plate being drilled with holes arranged in a geometrical pattern in compliance with the pattern chosen for the arrangement of the pins on the housing and calibrated so as to hold and to center the stems in the housing holes. The third part consists of a gripping device to lock the substrate of the housing fitted with its pins on the first metal plate. The materials chosen for the first metal plate have an expansion coefficient close to the expansion coefficient of the substrate of the housing in the temperature range at which the pins are to be fastened and this first metal plate is locked to the substrate of the housing during the fastening of the pins. Only the first metal plate is brought to this fastening temperature.

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